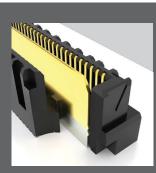


# **LOW-PROFILE GROUND PLANE**

## O STRIP<sup>®</sup> HIGH-SPEED INTERCONNECTS

- Choice of pitch: 0.50 mm, 0.635 mm and 0.80 mm
- Integral ground plane rated to 25 A
- 5 25 mm stack heights
- Reliable signal intergrity performance
- Mating/alignment "friendly" Blade and Beam contact system
- 40 180 signal pins / 14 – 60 differential pairs
- Right-angle and edge mount available
- 38 AWG micro coax and 30 AWG twinax cable assemblies rated to 14 Gbps
- Rugged guide post, latching and alignment pin options
- Compatible with mPOWER® micro power system for power/signal flexibility



#### INTEGRAL GROUND PLANE

- Surface mount ground plane between two signal rows improves electrical performance
- Significantly reduces row-to-row crosstalk
- Reduces coupling between pins within a row



### **SYSTEM**

• **QTH/QSH** – 0.50 mm Pitch Header & Socket QTS/QSS – 0.635 mm Pitch Header & Socket

• **QTE/QSE** – 0.80 mm Pitch Header & Socket

• HQCD/EQCD – 0.50 mm & 0.80 mm Pitch Micro Coax Cable Assemblies

**RIP**<sup>®</sup>

HODP/EQDP – 0.50 mm & 0.80 mm Pitch Twinax Cable Assemblies

#### For more High-Speed Board-to-Board Solutions, please visit samtec.com/mezzanine